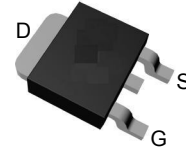


- 30V/100A
- $R_{DS(ON)}=3m\Omega$  (typ) @VGS=10V  
 $R_{DS(ON)}=4.5m\Omega$  (typ) @VGS=4.5V
- 100% UIS & RG Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

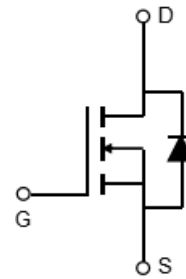
## Applications

- Power Management for Industrial Converters

## Pin Configuration



Top View of TO-252



N-Channel MOSFET

**Absolute Maximum Ratings** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Rating	Unit	
<b>Common Ratings</b>				
$V_{DSS}$	Drain-Source Voltage	30	V	
$V_{GSS}$	Gate-Source Voltage	$\pm 20$		
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$	100	A
		$T_C=100^\circ\text{C}$	39	
$I_{DM}$	Pulsed Drain Current	$T_C=25^\circ\text{C}$	160	
$P_D$	Power Dissipation	$T_A=25^\circ\text{C}$	3.6	W
$P_D$	Power Dissipation	$T_C=25^\circ\text{C}$	52	W
$T_{STG}, T_j$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
$I_D$	Continuous Drain Current	$T_A=25^\circ\text{C}$	18	A
		$T_A=70^\circ\text{C}$	14	

**Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress rating only and functional device operation is not implied**

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	30	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_j=85^\circ C$	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1	-	2.5	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=20A$	-	3	4.5	m $\Omega$
		$V_{GS}=4.5V, I_{DS}=15A$	-	4.5	6.8	
<b>Body Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage	$I_{SD}=40A, V_{GS}=0V$	-	0.7	1.3	V
<b>Dynamic Characteristics<sup>e</sup></b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=10V,$ Frequency=1.0MHz	-	1356	-	pF
$C_{oss}$	Output Capacitance		-	55	-	
$C_{rss}$	Reverse transfer capacitance		-	45	-	
$t_{d(ON)}$	Turn-on delay Time	$V_{GS}=10V, V_{DS}=15V$ $R_G=1.8\Omega, I_D=20A, R_L=30\Omega$	-	8	-	nS
$t_r$	Turn-on rise Time		-	9	-	
$t_{d(OFF)}$	Turn-off delay Time		-	32	-	
$t_f$	Turn-off rise Time		-	6	-	
<b>Gate Charge Characteristics<sup>e</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V, I_{DS}=20A$	-	23	-	
$Q_{gs}$	Gate-Source Charge		-	5	-	
$Q_{gd}$	Gate-Drain Charge		-	3	-	

**Note: 1. Pulse test: pulse width $\leq$ 300uS, duty cycle $\leq$ 2%**

**2.Static parameters are based on package level with recommended wire bonding**

**TYPICAL CHARACTERISTICS (25°C Unless Note)**

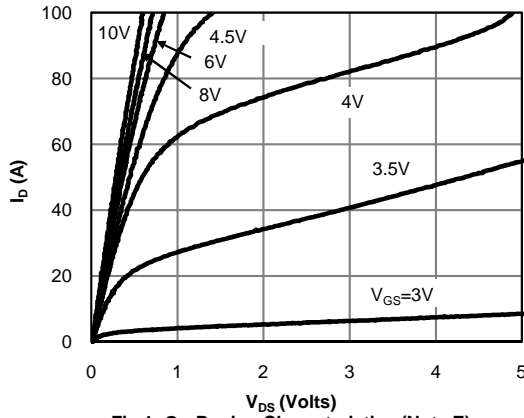


Fig 1: On-Region Characteristics (Note E)

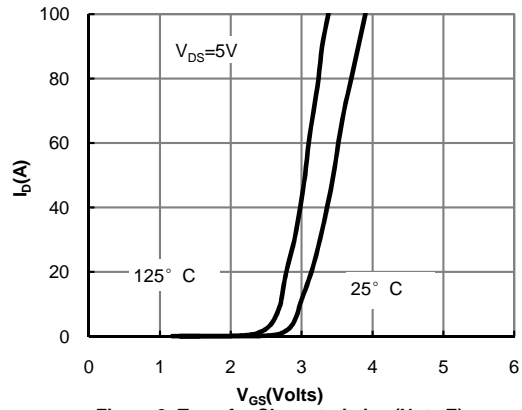


Figure 2: Transfer Characteristics (Note E)

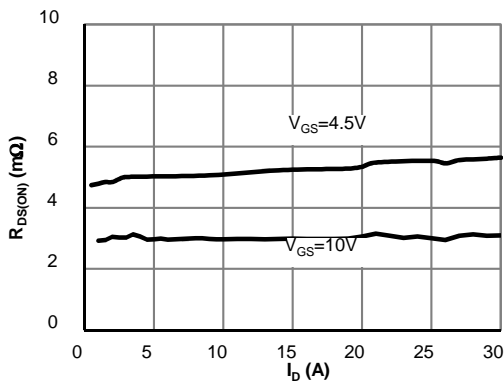


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

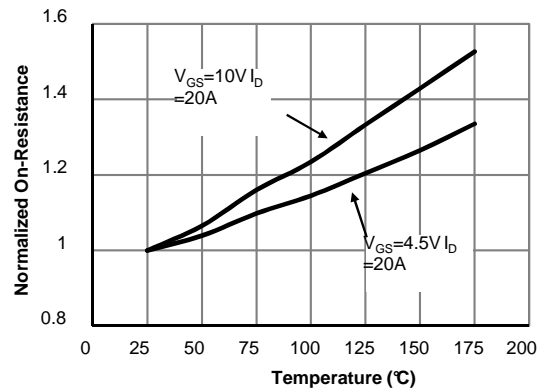


Figure 4: On-Resistance vs. Junction Temperature (Note E)

**TYPICAL CHARACTERISTICS (continuous)**

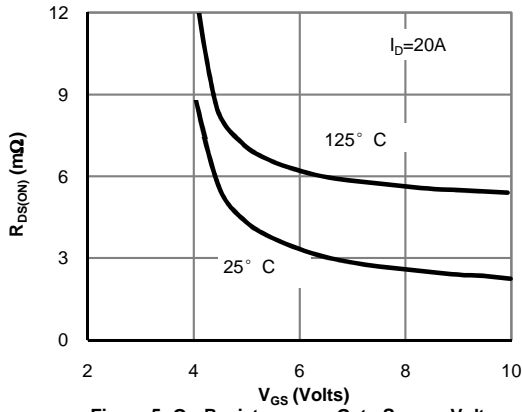


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

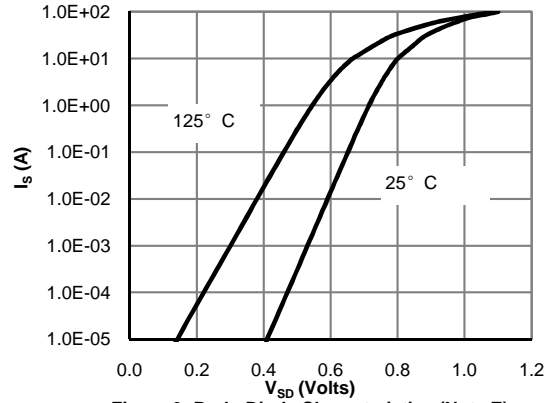


Figure 6: Body-Diode Characteristics (Note E)

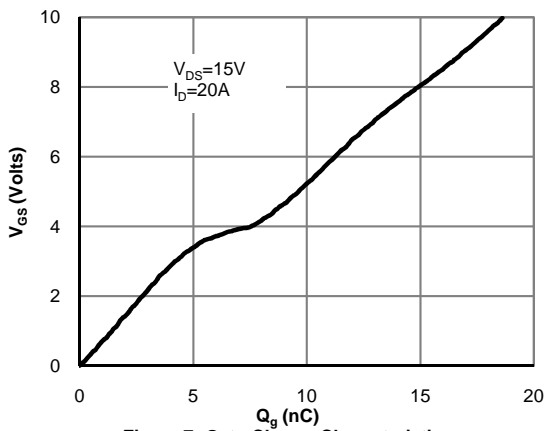


Figure 7: Gate-Charge Characteristics

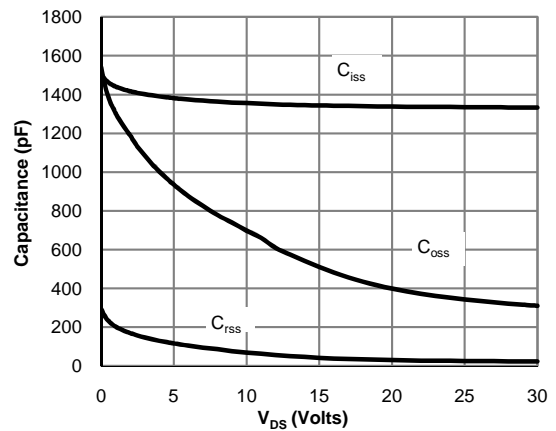


Figure 8: Capacitance Characteristics

**TYPICAL CHARACTERISTICS (continuous)**

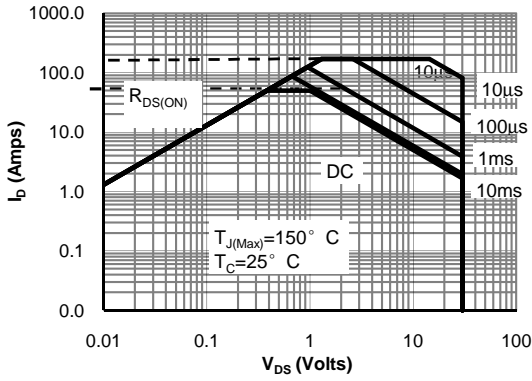


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

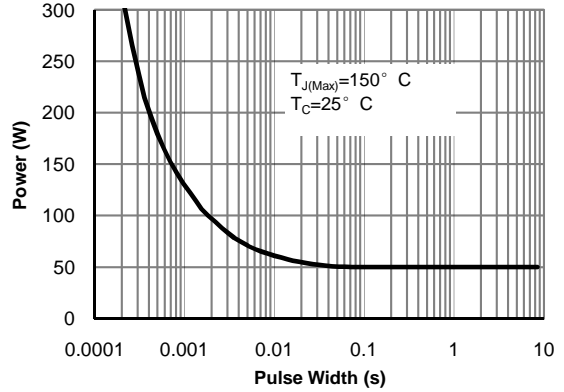


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

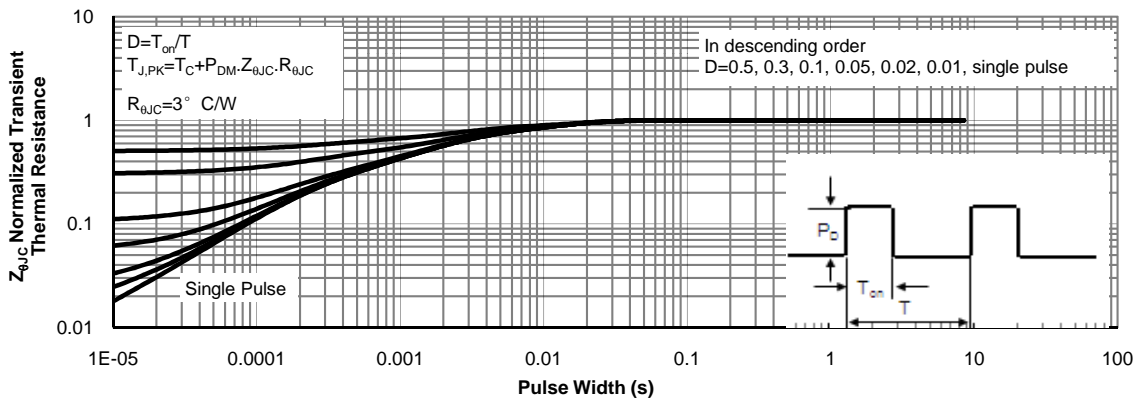
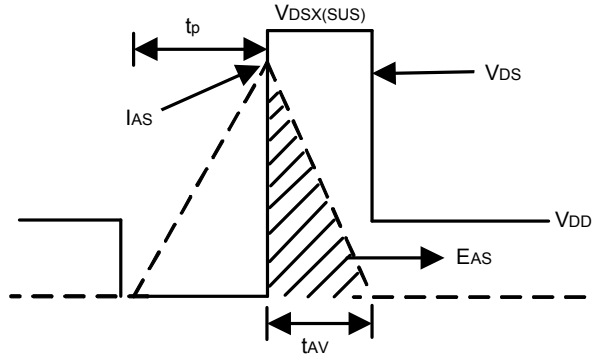
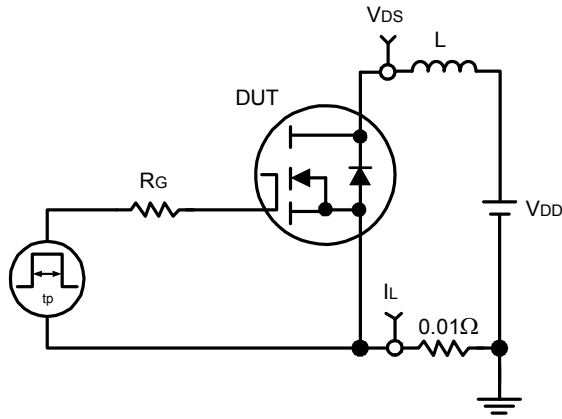
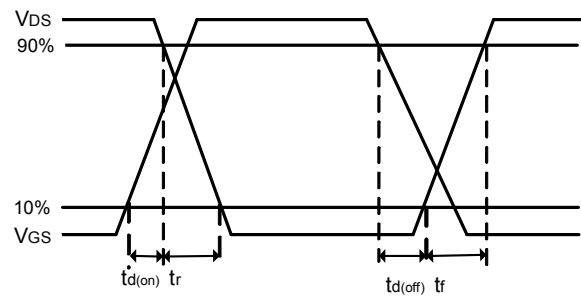
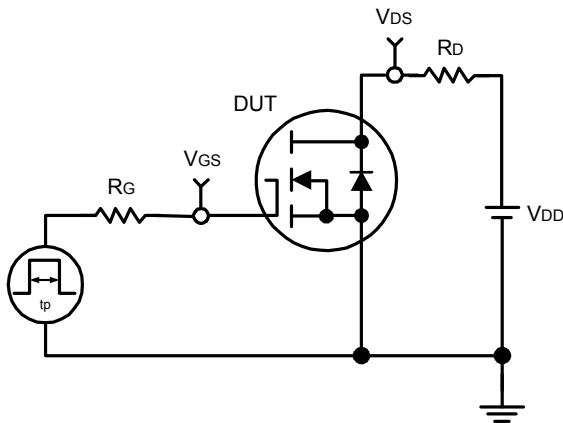


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

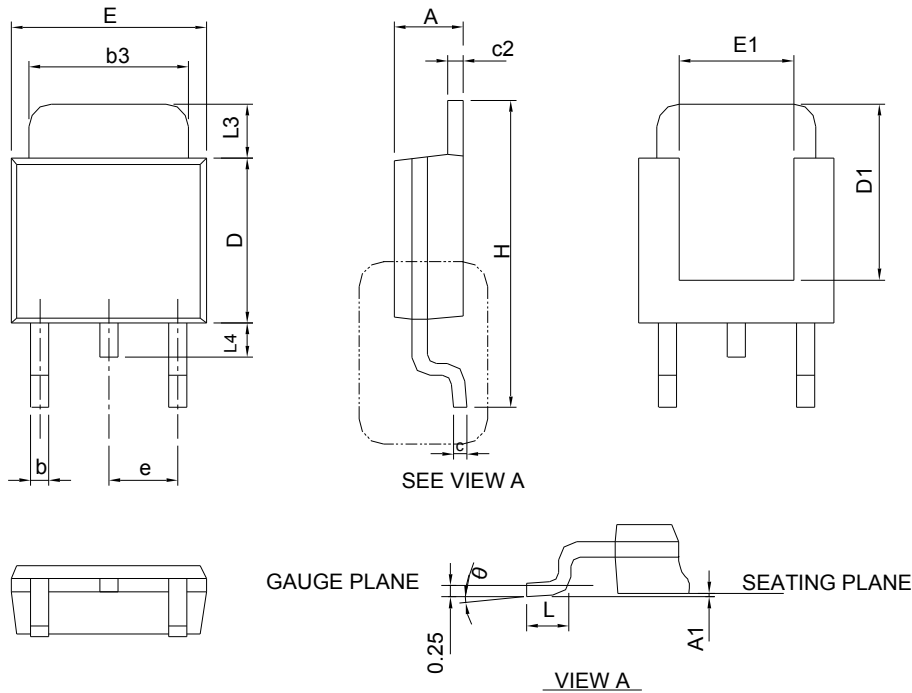
### Avalanche Test Circuit and Waveforms



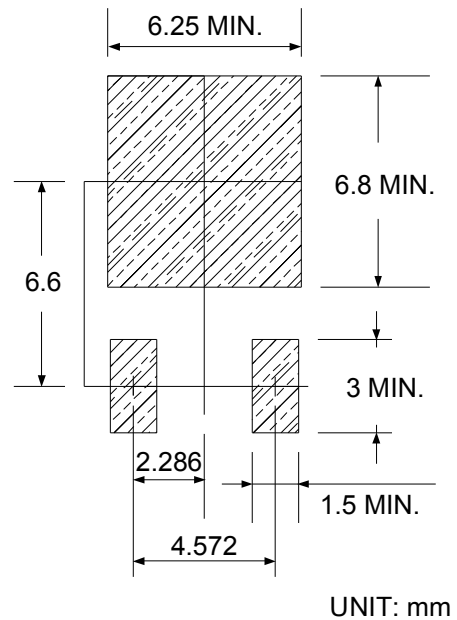
### Switching Time Test Circuit and Waveforms



## Package Information

**TO-252**


SYMBOLS	TO-252			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1	-	0.13	-	0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4	-	1.02	-	0.040
θ	0°	8°	0°	8°

**RECOMMENDED LAND PATTERN**


Note : Follow JEDEC TO-252-2 .